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(54) **SURFACE-TREATED COPPER FOIL,
COPPER-CLAD LAMINATE AND PRINTED
WIRING BOARD USING THE
SURFACE-TREATED COPPER FOIL**

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(57) **ABSTRACT**

A surface-treated copper foil includes, on at least one surface of an untreated copper foil, a finely roughened layer formed of copper particles in which primary particles have a particle size of 10 nm to 110 nm or less, and a heat-resistant-treatment layer containing nickel and phosphorus, wherein a treated surface has a surface area ratio of 5.1 or more per 1 m² of a two-dimensional area, the surface area ratio being calculated from a specific surface area measured by a krypton gas adsorption BET method, and a coating mass of the nickel is 2 mg or more per 1 m² of a surface area.

